

Assemblies, Related Materials and Processes For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 15.0002

CB Certificate No.: E039/CA

Schedule Number: IECQ-C BSI 15.0002-S		Rev No.: 12	Revision Date: 201	18/11/09 Page 1 of 2	
Board Types:	Rigid single and double-sided with plain holes BS 123100-00				
	Rigid double-sided with	BS 123200-003			
	Rigid multi-layer			BS 123300-003	
	Flexible single and double sided without-through BS 12 connections				
	Flexible double-sided w	BS 123500-003			
	Flex-rigid multi-layer wit	BS 123600-003			
Base Materials:	Epoxide Woven Glass Polyimide Film				
Board Size:	610 mm x 457 mm 610 mm x 457 mm 610 mm x 457 mm 610 mm x 457 mm	Maximum Maximum Maximum Maximum		BS EN 123 300 23 100, BS EN 123 200 23 400, BS EN 123 500 BS EN 123 600	
Conductors:	Minimum Width: Minimum Spacing:	100 μm 100 μm	± 25 μm ± 25 μm		
Number of Layers:	24 Maximum				
Plated-through hole diameter:	0.30 mm Minimum 0.30 mm Minimum	finished drilled	for component mounting via hole		
Aspect ratio:	9 : 1 Maximum				

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IEC QUALITY ASSESSMENT SYSTEM (IECQ) covering Electronic Components,

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Finishes:	 * Hot Air Solder Levelling Liquid Photopolymer Solder Resist Legend; Thermally Cured ENIG surface finish 					
Additional:	Bonded Heats	sinks:	Anodised Aluminium			
	Blind and Buri Rigidisers / St					

* These finishes meet the solderability requirements after accelerated ageing.

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